<table>
<thead>
<tr>
<th>Layer</th>
<th>Name</th>
<th>Material</th>
<th>Thickness</th>
<th>Conversion</th>
<th>Board Layer Stack</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>Top Overlay</td>
<td>Solder Resist</td>
<td>0.030in</td>
<td>0.8mm</td>
<td>Top Overlay</td>
</tr>
<tr>
<td>2</td>
<td>Top Solder</td>
<td>FR-4</td>
<td>0.025in</td>
<td>0.6mm</td>
<td>Top Solder</td>
</tr>
<tr>
<td>3</td>
<td>Top Layer</td>
<td>Copper Clad</td>
<td>0.020in</td>
<td>0.5mm</td>
<td>Top Layer</td>
</tr>
<tr>
<td>4</td>
<td>Button Layer</td>
<td>Solder Resist</td>
<td>0.030in</td>
<td>0.8mm</td>
<td>Button Layer</td>
</tr>
</tbody>
</table>

**Design Information**

- **Name:** VHDL TRACK
- **Version:** A
- **Device:** 0.2 mm
- **VCC:** 5 V
- **GND:** 0 V
- **Reference:** UMSI PC/0-12 TYPE 3 CLASS 1
- **Material:** FR-4 High Tg
- **Solder Resist:** ENIG ENE-6022 TYPE 3 CLASS 1
- **Board Finish:** ENE-6022 TYPE 3 CLASS 1
- **Surface Finish:** Enamelled

**Assembly Reference**

- **Reel:** 1000-5000
- **Placing:** 10000
- **Handling:** 20000
- **Components:** MARKED "OEM" SHOULD NOT BE ORDERED AS MARKED "OEM""
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